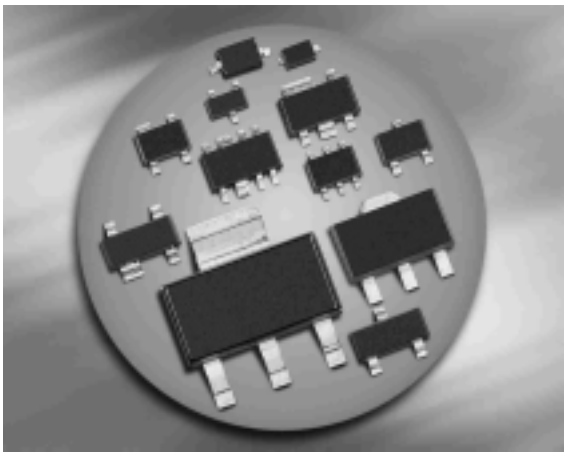
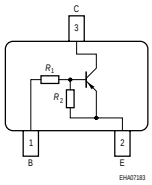
PNP Silicon Digital Transistor

- Switching circuit, inverter, interface circuit, driver circuit
- Built in resistor (R_1=2.2kΩ, R_2=2.2kΩ)
- BCR153U: Two internally isolated transistors with good matching in one multichip package



BCR153F/L3
BCR153T



Type	Marking	Pin Configuration						Package
BCR153F	WBs	1=B	2=E	3=C	-	-	-	TSFP-3
BCR153L3	WB	1=B	2=E	3=C	-	-	-	TSLP-3-4
BCR153T	WB	1=B	2=E	3=C	-	-	-	SC75

Maximum Ratings

Parameter	Symbol	Value	Unit
Collector-emitter voltage	V_{CEO}	50	V
Collector-base voltage	V_{CBO}	50	
Input forward voltage	$V_{i(fwd)}$	20	
Input reverse voltage	$V_{i(rev)}$	10	
Collector current	I_C	100	mA
Total power dissipation	P_{tot}		mW
BCR153F, $T_S \leq 128°C$		250	
BCR153L3, $T_S \leq 135°C$		250	
BCR153T, $T_S \leq 109°C$		250	
Junction temperature	T_j	150	°C
Storage temperature	T_{stg}	-65 ... 150	

Thermal Resistance

Parameter	Symbol	Value	Unit
Junction - soldering point[1)]	R_{thJS}		K/W
BCR153F		≤ 90	
BCR153L3		≤ 60	
BCR153T		≤ 165	

Electrical Characteristics at T_A = 25°C, unless otherwise specified

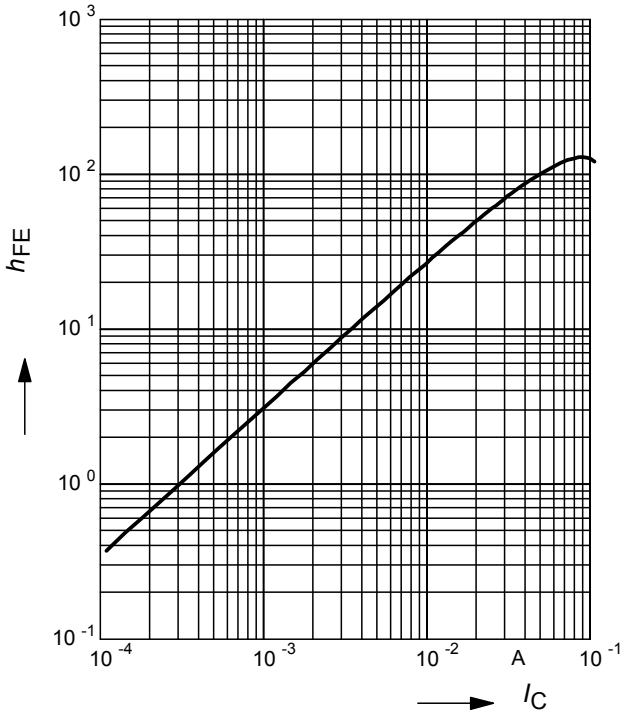
Parameter	Symbol	Values			Unit
		min.	typ.	max.	
DC Characteristics					
Collector-emitter breakdown voltage I_C = 100 µA, I_B = 0	$V_{(BR)CEO}$	50	-	-	V
Collector-base breakdown voltage I_C = 10 µA, I_E = 0	$V_{(BR)CBO}$	50	-	-	
Collector-base cutoff current V_{CB} = 40 V, I_E = 0	I_{CBO}	-	-	100	nA
Emitter-base cutoff current V_{EB} = 10 V, I_C = 0	I_{EBO}	-	-	3.5	mA
DC current gain[2)] I_C = 20 mA, V_{CE} = 5 V	h_{FE}	20	-	-	-
Collector-emitter saturation voltage[2)] I_C = 20 mA, I_B = 1 mA	V_{CEsat}	-	-	0.3	V
Input off voltage I_C = 100 µA, V_{CE} = 5 V	$V_{i(off)}$	0.8	-	1.5	
Input on voltage I_C = 2 mA, V_{CE} = 0.3 V	$V_{i(on)}$	0.8	-	2.5	
Input resistor	R_1	1.5	2.2	2.9	kΩ
Resistor ratio	R_1/R_2	0.9	1	1.1	-
AC Characteristics					
Transition frequency I_C = 10 mA, V_{CE} = 5 V, f = 100 MHz	f_T	-	200	-	MHz
Collector-base capacitance V_{CB} = 10 V, f = 1 MHz	C_{cb}	-	3	-	pF

[1]For calculation of R_{thJA} please refer to Application Note Thermal Resistance

[2]Pulse test: t < 300µs; D < 2%

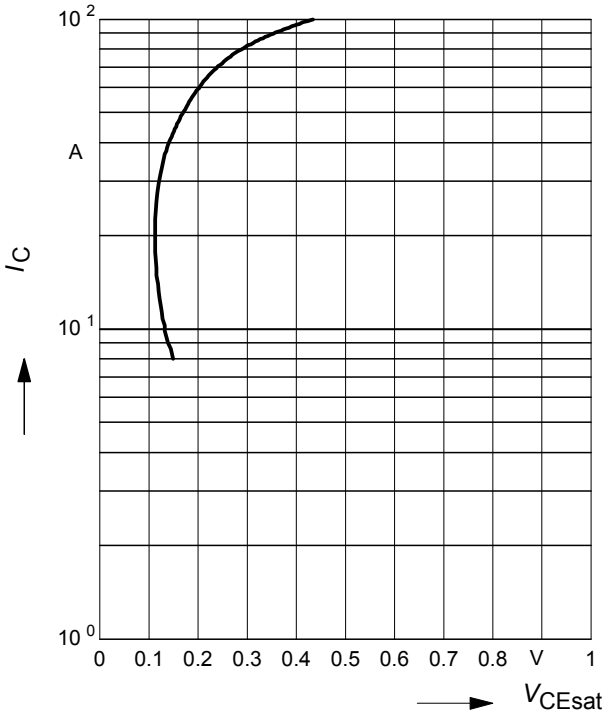
DC current gain $h_{FE} = f(I_C)$

V_{CE} = 5V (common emitter configuration)



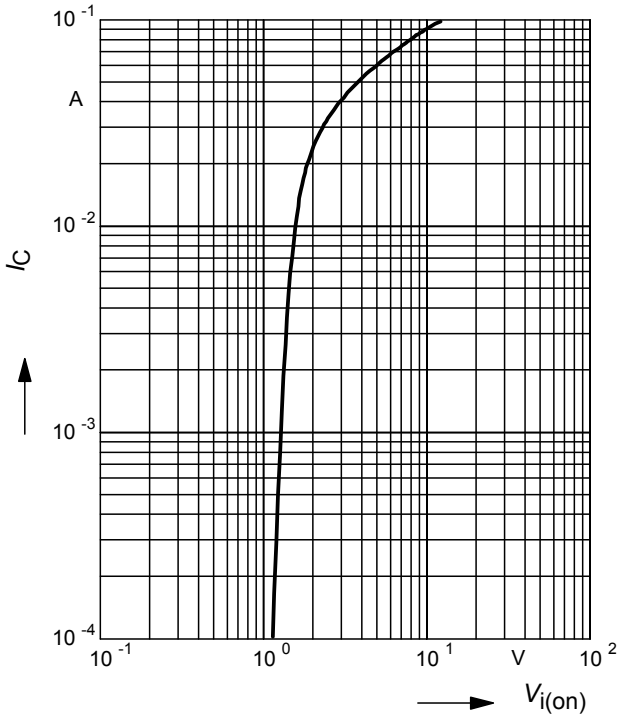
Collector-emitter saturation voltage

$V_{CEsat} = f(I_C)$, h_{FE} = 20



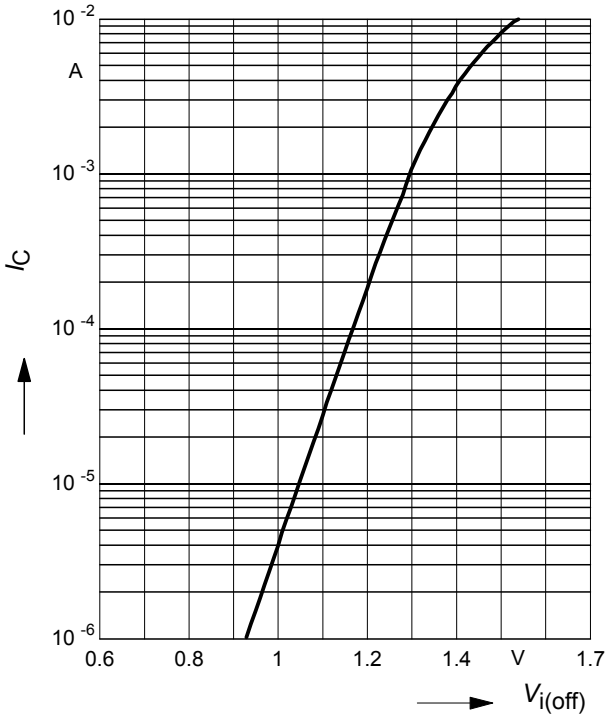
Input on Voltage $V_{i(on)} = f(I_C)$

V_{CE} = 0.3V (common emitter configuration)



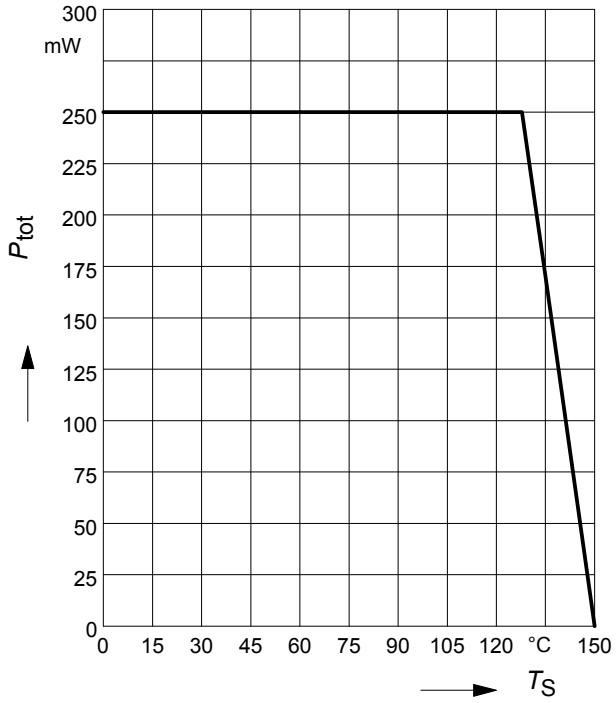
Input off voltage $V_{i(off)} = f(I_C)$

V_{CE} = 5V (common emitter configuration)



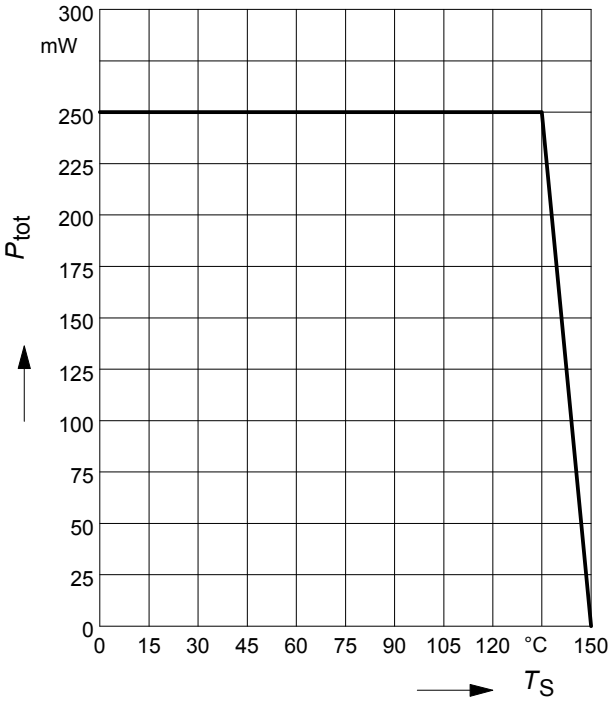
Total power dissipation $P_{tot} = f(T_S)$

BCR153F



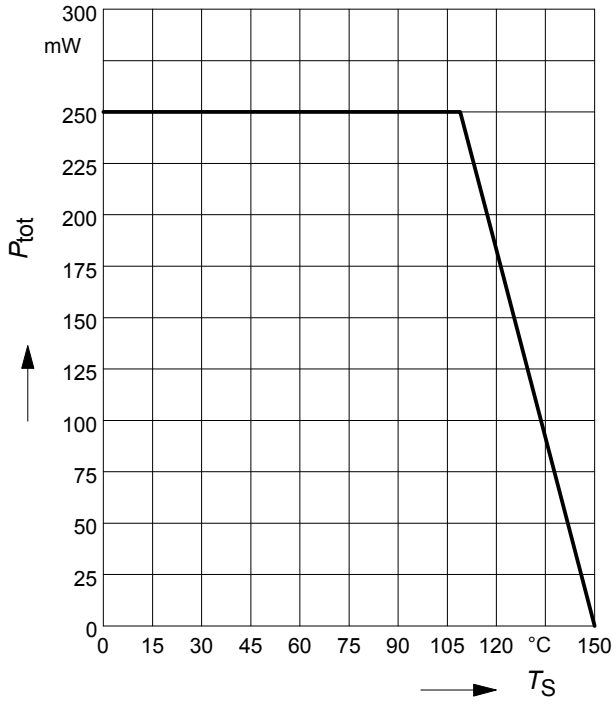
Total power dissipation $P_{tot} = f(T_S)$

BCR153L3



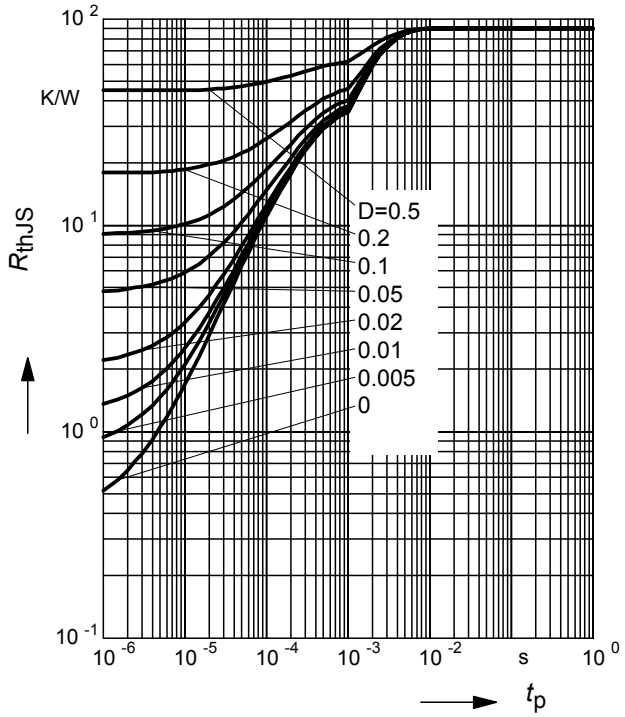
Total power dissipation $P_{tot} = f(T_S)$

BCR153T



Permissible Puls Load $R_{thJS} = f(t_p)$

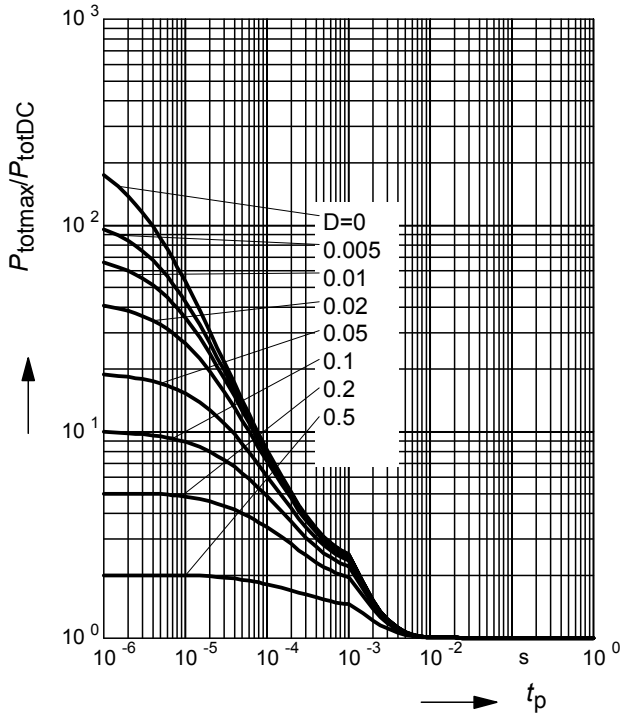
BCR153F



Permissible Pulse Load

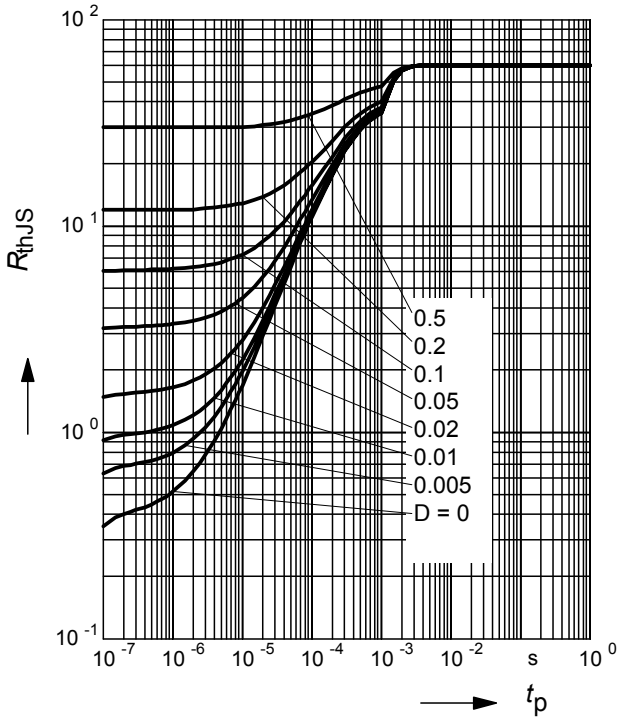
$P_{totmax}/P_{totDC} = f(t_p)$

BCR153F



Permissible Puls Load $R_{thJS} = f(t_p)$

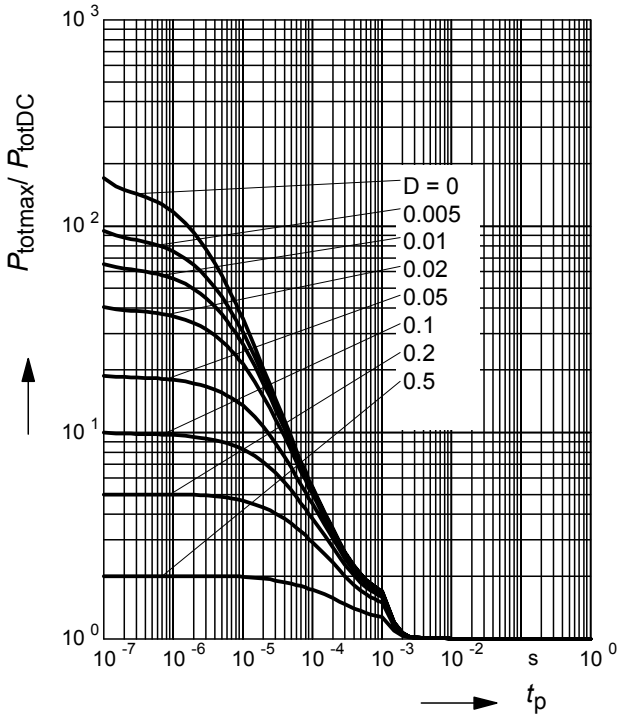
BCR153L3



Permissible Pulse Load

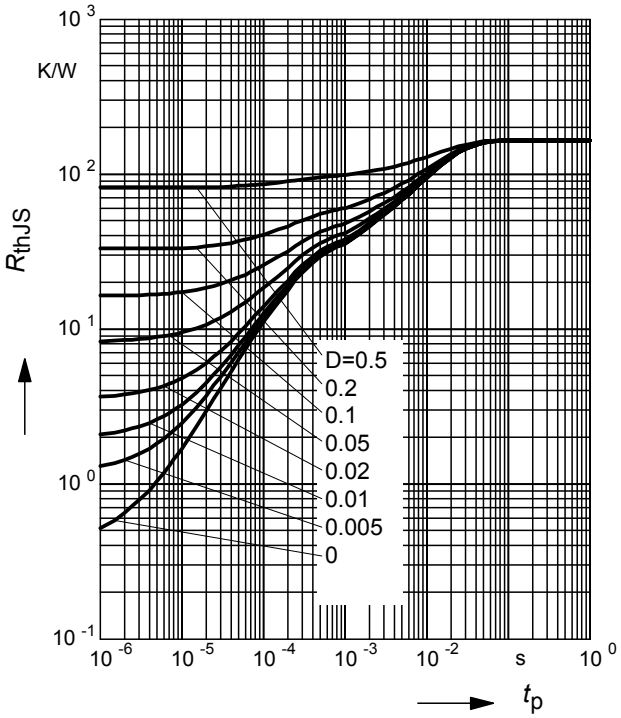
$P_{totmax}/P_{totDC} = f(t_p)$

BCR153L3



Permissible Puls Load $R_{thJS} = f(t_p)$

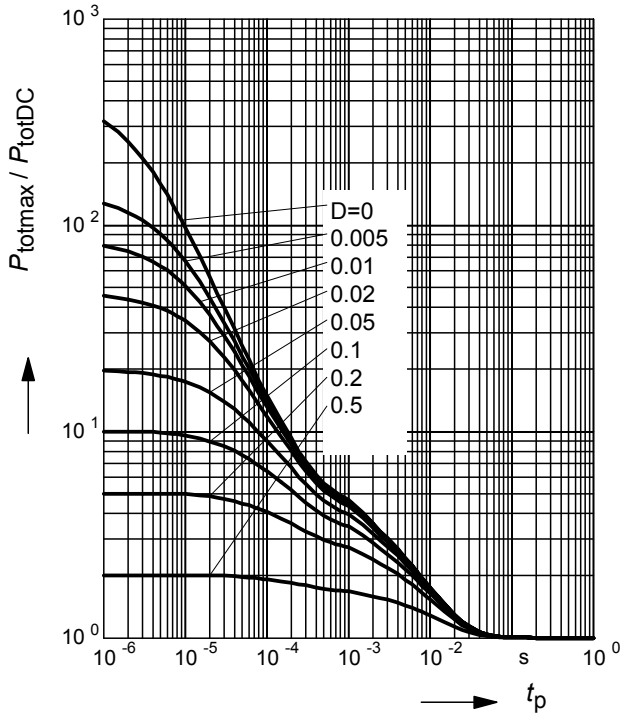
BCR153T



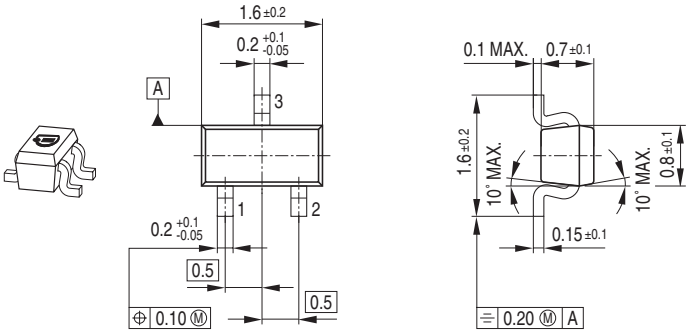
Permissible Pulse Load

$P_{totmax}/P_{totDC} = f(t_p)$

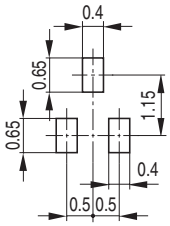
BCR153T



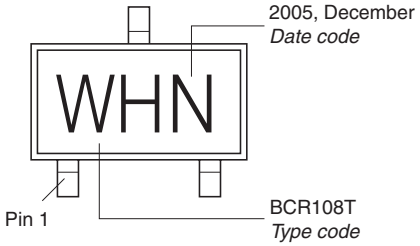
Package Outline



Foot Print

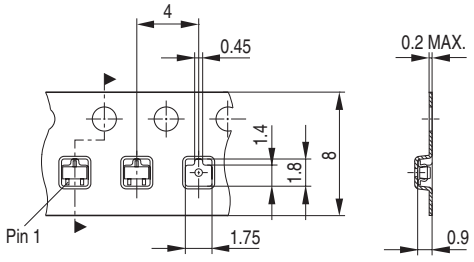


Marking Layout (Example)



Standard Packing

Reel ø180 mm = 3.000 Pieces/Reel
Reel ø330 mm = 10.000 Pieces/Reel

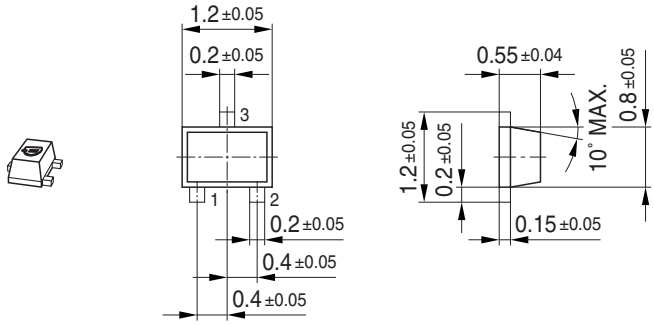


Date Code marking for discrete packages with one digit (SCD80, SC79, SC75[1)]) CES-Code

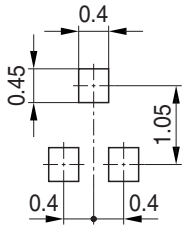
Month	2003	2004	2005	2006	2007	2008	2009	2010	2011	2012	2013	2014
01	a	p	A	P	a	p	A	P	a	p	A	P
02	b	q	B	Q	b	q	B	Q	b	q	B	Q
03	c	r	C	R	c	r	C	R	c	r	C	R
04	d	s	D	S	d	s	D	S	d	s	D	S
05	e	t	E	T	e	t	E	T	e	t	E	T
06	f	u	F	U	f	u	F	U	f	u	F	U
07	g	v	G	V	g	v	G	V	g	v	G	V
08	h	x	H	X	h	x	H	X	h	x	H	X
09	j	y	J	Y	j	y	J	Y	j	y	J	Y
10	k	z	K	Z	k	z	K	Z	k	z	K	Z
11	l	2	L	4	l	2	L	4	l	2	L	4
12	n	3	N	5	n	3	N	5	n	3	N	5

1) New Marking Layout for SC75, implemented at October 2005.

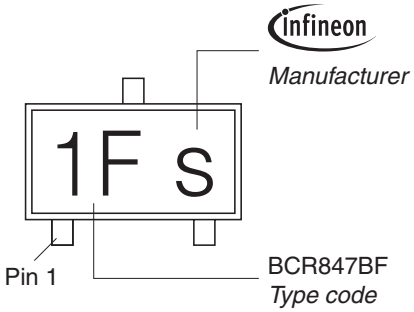
Package Outline



Foot Print

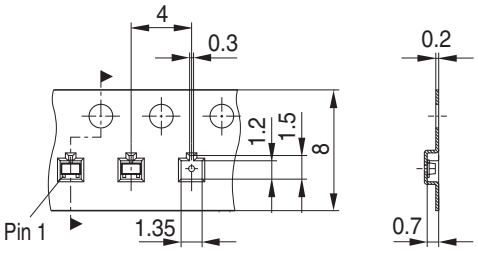


Marking Layout (Example)

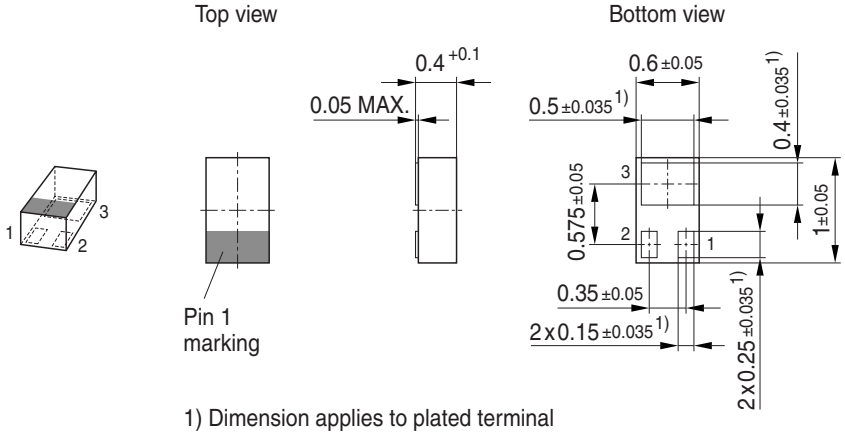


Standard Packing

Reel ø180 mm = 3.000 Pieces/Reel
Reel ø330 mm = 10.000 Pieces/Reel



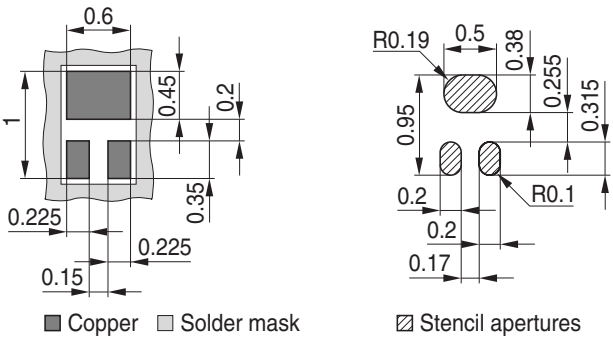
Package Outline



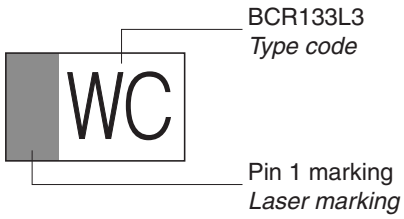
1) Dimension applies to plated terminal

Foot Print

For board assembly information please refer to Infineon website "Packages"

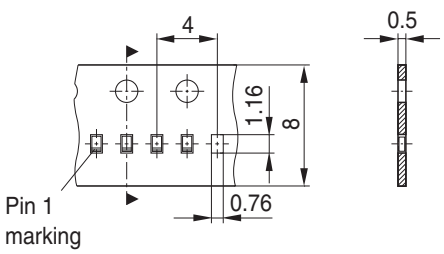


Marking Layout



Standard Packing

Reel ø180 mm = 15.000 Pieces/Reel



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